AMPLE Electronic Technology CO., LTD

Stock code:4760

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2026 /Q2

www.ampletec.com.tw

Disclaimer

- The presentation and discussion contain certain forward-looking statements with respect to the results of operation, financial condition and current expectation.
- The forward-looking statements are subject to known and unknown uncertainties and risks that could cause actual results to differ materially from those expressed or implied by such statements. Such risks and uncertainties include but are not limited to the impact of competitive products and pricing, timely project acceptance by our customers, timely introduction of new technologies, ability to ramp new needs into products, financial stability in end markets, and other risks that AMPLE can not control.
- The forward-looking statements in this release reflect the current belief of AMPLE as of the date of this release and AMPLE undertakes no obligation to update these forward-looking statements for events or circumstances that occur subsequent to such date.

Introduction

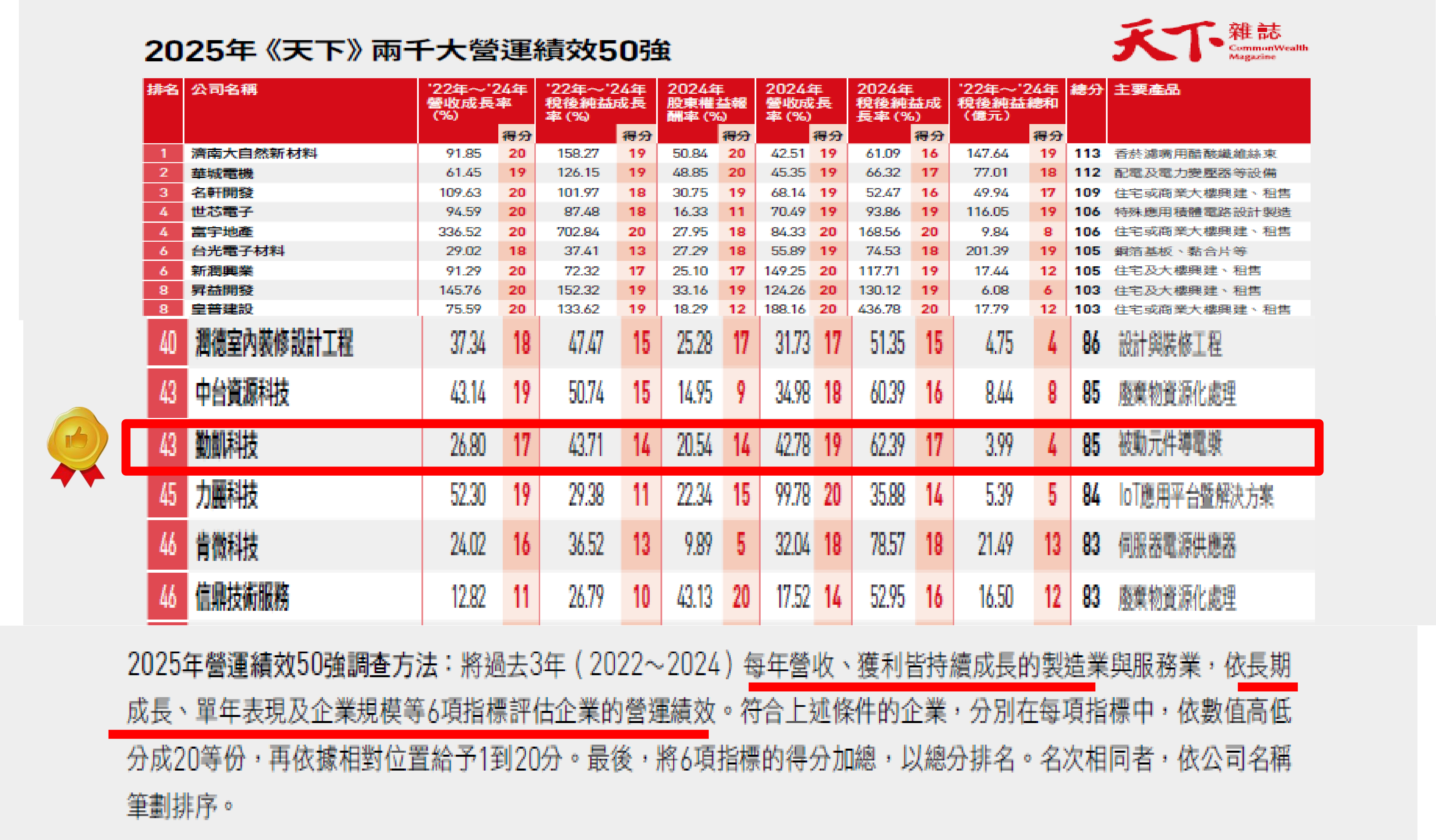
- Established: **June 8, 2007**
- Capital: ~ NTD $ 322 Million
- Main Products：

Design, Manufacture, and Sales of conductive materials for advanced packaging interconnects, thermal materials, and ceramic components.

- Location：

No.32, Dayou 3rd St., Daliao Dist,
Kaohsiung City, Taiwan

Year 2025《CommonWealth Magazine》Top 50 in 2,000 Operational Performance



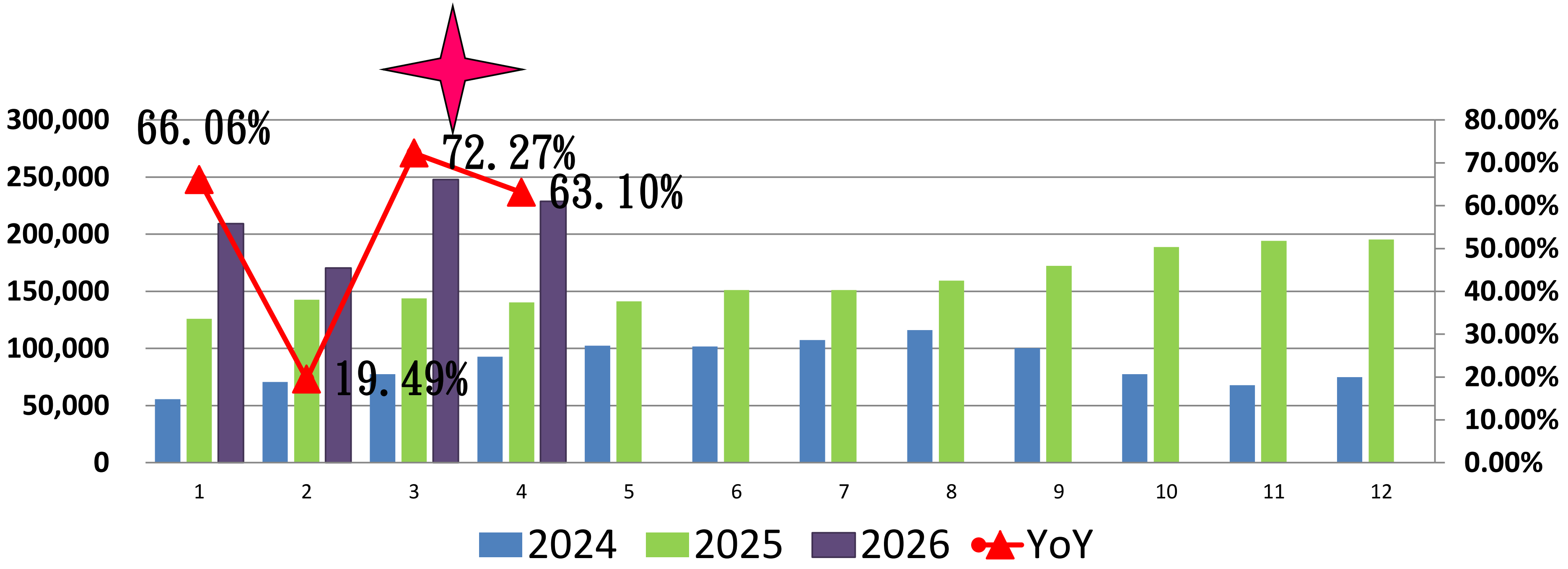
2025年《天下》兩千大營運績效50強

排名	公司名稱	'22年～'24年營收成長率（%）	得分	'22年～'24年稅後純益成長率（%）	得分	2024年股東權益報酬率（%）	得分	2024年營收成長率（%）	得分	2024年稅後純益成長率（%）	得分	'22年～'24年稅後純益總和（億元）	得分	總分	主要產品
1	濟南大自然新材料	91.85	20	158.27	19	50.84	20	42.51	19	61.09	16	147.64	19	113	香菸濾嘴用醋酸纖維絲束
2	華城電機	61.45	19	126.15	19	48.85	20	45.35	19	66.32	17	77.01	18	112	配電及電力變壓器等設備
3	名軒開發	109.63	20	101.97	18	30.75	19	68.14	19	52.47	16	49.94	17	109	住宅或商業大樓興建、租售
4	世芯電子	94.59	20	87.48	18	16.33	11	70.49	19	93.86	19	116.05	19	106	特殊應用積體電路設計製造
4	富宇地產	336.52	20	702.84	20	27.95	18	84.33	20	168.56	20	9.84	8	106	住宅或商業大樓興建、租售
6	台光電子材料	29.02	18	37.41	13	27.29	18	55.89	19	74.53	18	201.39	19	105	銅箔基板、黏合片等
6	新潤興業	91.29	20	72.32	17	25.10	17	149.25	20	117.71	19	17.44	12	105	住宅及大樓興建、租售
8	昇益開發	145.76	20	152.32	19	33.16	19	124.26	20	130.12	19	6.08	6	103	住宅及大樓興建、租售
8	皇普建設	75.59	20	133.62	19	18.29	12	188.16	20	436.78	20	17.79	12	103	住宅或商業大樓興建、租售
40	潤德室內裝修設計工程	37.34	18	47.47	15	25.28	17	31.73	17	51.35	15	4.75	4	86	設計與裝修工程
43	中台資源科技	43.14	19	50.74	15	14.95	9	34.98	18	60.39	16	8.44	8	85	廢棄物資源化處理
43	勤凱科技	26.80	17	43.71	14	20.54	14	42.78	19	62.39	17	3.99	4	85	被動元件導電漿
45	力麗科技	52.30	19	29.38	11	22.34	15	99.78	20	35.88	14	5.39	5	84	IoT應用平台暨解決方案
46	肯微科技	24.02	16	36.52	13	9.89	5	32.04	18	78.57	18	21.49	13	83	伺服器電源供應器
46	信鼎技術服務	12.82	11	26.79	10	43.13	20	17.52	14	52.95	16	16.50	12	83	廢棄物資源化處理

2025年營運績效50強調查方法：將過去3年（2022～2024）每年營收、獲利皆持續成長的製造業與服務業，依長期成長、單年表現及企業規模等6項指標評估企業的營運績效。符合上述條件的企業，分別在每項指標中，依數值高低分成20等份，再依據相對位置給予1到20分。最後，將6項指標的得分加總，以總分排名。名次相同者，依公司名稱筆劃排序。

2025 Monthly Revenue Double Digit Growth YoY

	Jan	Feb	Mar	Apr	May	June	July	Aug	Sep	Oct	Nov	Dec	Accumulated
2021	134,517	140,857	146,066	154,568	155,720	162,519	166,611	165,828	162,539	131,852	112,998	101,094	1,735,167
2022	100,068	80,781	102,422	103,193	100,299	100,052	78,029	54,894	45,927	47,703	53,678	61,045	928,090
2023	55,712	70,767	77,474	92,910	102,508	101,741	107,330	116,087	100,286	77,414	67,862	74,912	1,045,002
2024	89,533	75,599	100,786	106,535	140,287	121,125	126,057	135,482	169,400	168,439	142,406	116,230	1,491,879
2025	126,050	142,604	143,812	140,320	141,377	151,040	151,219	159,285	172,303	188,815	194,189	195,386	1,906,400
2026	209,318	170,398	247,746	228,860									856,322
YoY	66.06%	19.49%	72.27%	63.10%									
MoM	7.13%	-18.59%	45.39%	-7.62%									



ample
ELECTRONIC TECHNOLOGY

Statements of Comprehensive- 2026 Q1 Record High

NT$ 千元	2022	2023	2024	2025	2026.Q1		YoY	2025.Q1
營業收入	928,090	1,045,002	1,491,879	1,906,400	627,462		52%	412,467
營業毛利	194,267	224,069	326,055	410,118	123,851		29%	95,735
毛利率(%)	21%	21%	22%	22%	20%		-13%	23%
營業費用	(89,559)	(95,247)	(104,018)	(121,941)	(34,682)		22%	(28,497)
營業費用率(%)	9%	9%	9%	6%	6%		-14%	7%
營業淨利	104,708	128,822	222,037	288,177	89,169		33%	67,238
營業淨利率(%)	12%	12%	15%	16%	14%		-13%	16%
營業外收支淨額	11,709	14,345	15,758	(9,720)	9,965		35%	7,404
稅前淨利	116,417	143,167	237,795	278,457	99,134		33%	74,642
所得稅費用	(24,059)	(26,443)	(48,028)	(55,530)	(18,448)		32%	(13,965)
本期淨利	92,358	116,724	189,767	222,927	80,686		33%	60,677
淨利率(%)	10%	11%	13%	12%	13%		-13%	15%
每股盈餘(元)	3.08	3.9	6.3	7.05	2.55		33%	1.92
					5258			
折舊費用	24,873	23,682	23,271	22,590	5,258			5,553
資本支出	12,419	13,020	12,489	9,427	937			2,446

Dividend Policy

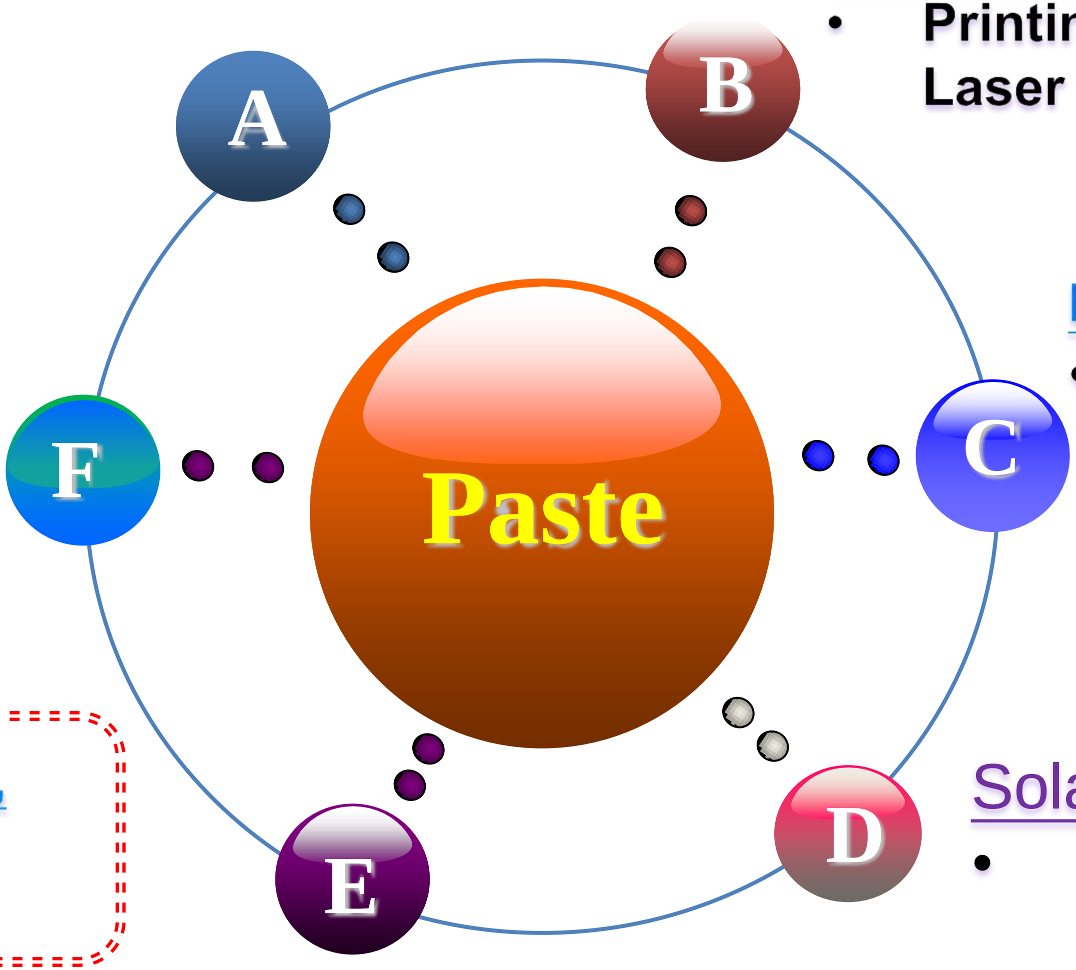
年度	2020	2021	2022	2023	2024	2025
EPS	4.74	6.7	3.08	3.9	6.3	7.05
Cash Dividend	3.2	4.5	2.2	2.7	3.7	4.5
Stock Dividend	–	–	–	–	0.5	0.2
Total Distributed Dividend	3.2	4.5	2.2	2.7	4.2	4.7
Interest Rate	67.51%	67.16%	71.43%	69.23%	66.67%	66.67%

Distributed dividends for 13 consecutive years!

Total dividends distributed: NTD$ 31.4875

(Cash dividend:NTD$ 25.12 + Stock dividend: NTD$ 6.3675)

Applications of Conductive paste



Passive Components

(Capacitor, Incuctor, Resistor)

- Ag paste
  Pd/Ag paste
  Cu paste
  Ni paste

Touch Panel:

- Printing type
  Laser Etching type

Membrane Switch:

- Ag paste

New Materials

- Al

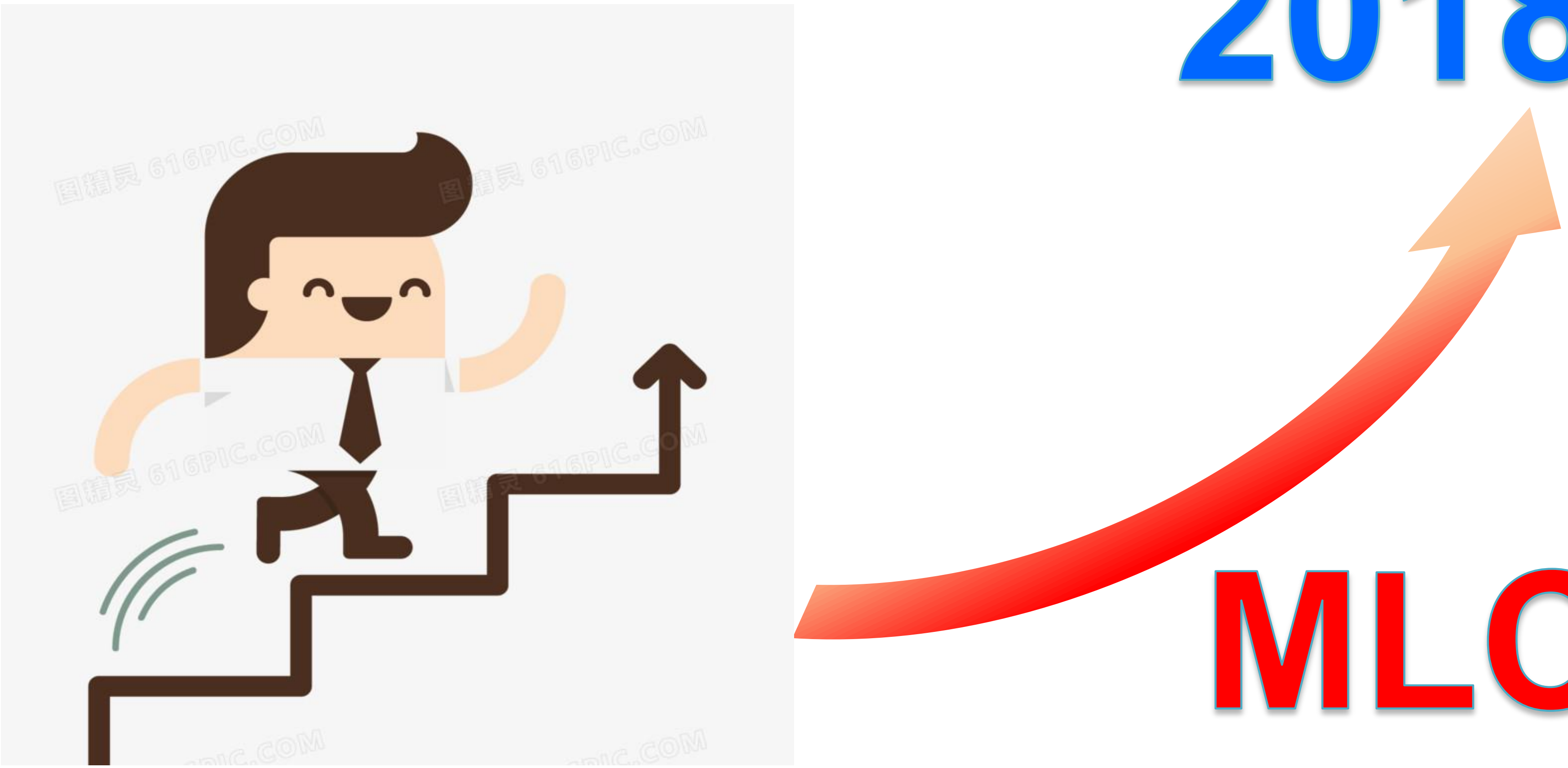
Solar Cell:

- Rear Ag paste

Semiconductor, LED Package:

- Ag paste

MLCC Strong demand will drive future growth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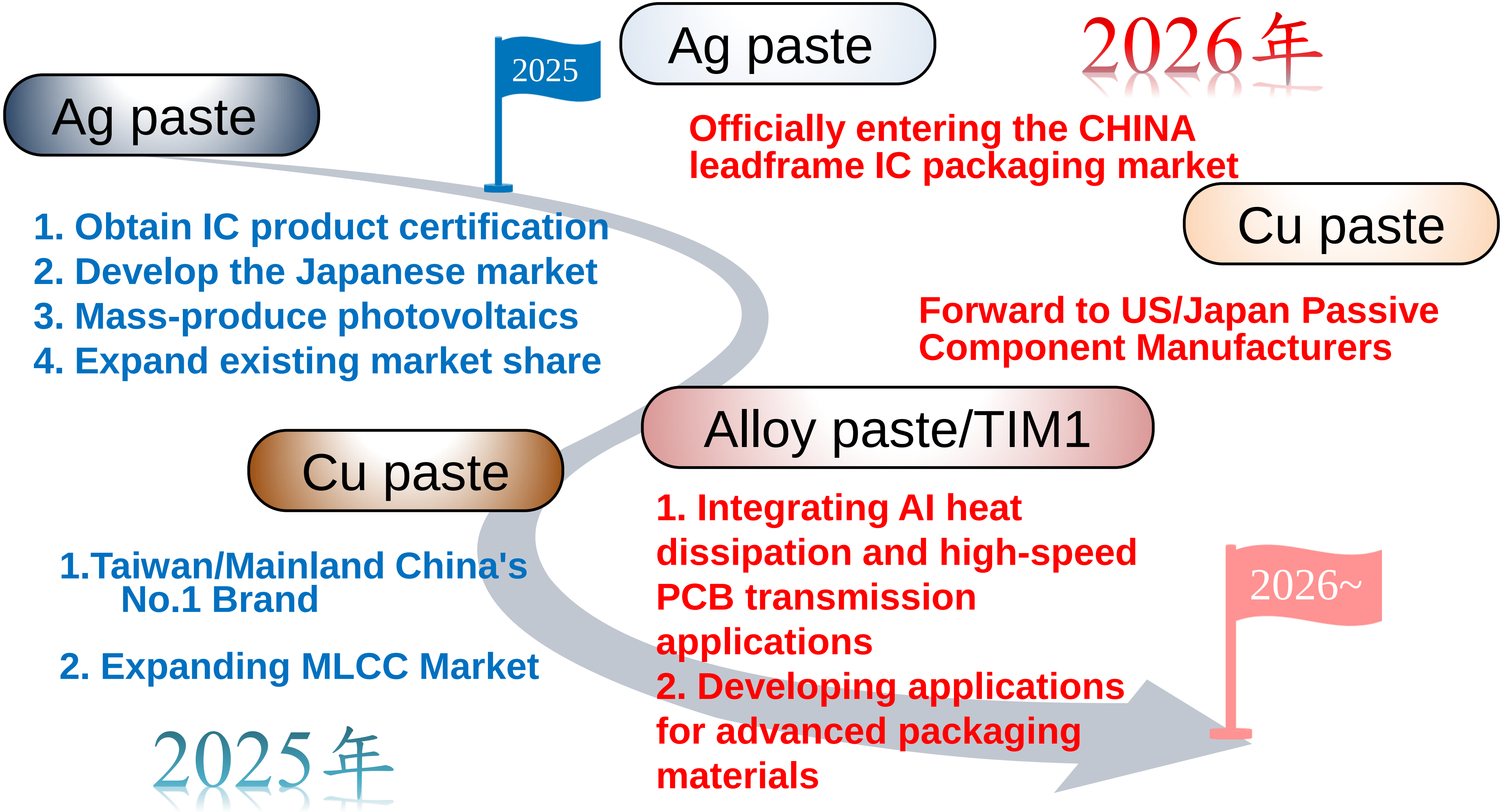
2018?!

MLCC

Development Milestones



2025年

Ag paste

1. Obtain IC product certification
2. Develop the Japanese market
3. Mass-produce photovoltaics
4. Expand existing market share

Cu paste

1.Taiwan/Mainland China's No.1 Brand

2. Expanding MLCC Market

2026年

Ag paste

Officially entering the CHINA leadframe IC packaging market

Cu paste

Forward to US/Japan Passive Component Manufacturers

Alloy paste/TIM1

1. Integrating AI heat dissipation and high-speed PCB transmission applications
2. Developing applications for advanced packaging materials

Our Goal 2026-2027

@ Land was acquired in 2026 to build new production capacity in order to meet future increased orders.

@ EPS YoY 20-25%

@ New application areas

COWOS Advanced packaging TIM1(Testing)
COPOS Advanced packagingTGV/FOPLP(Testing)
ABF (Ready)
Advanced Power Packaging(Testing)
High-speed Transmission in Flexible PCB
Robot sensors
TEST SOCKET Test fixture (Testing)

@ Increase the proportion of High-Margin products

Next-generation heat dissipation: semi-sintered adhesive/liquid metal

- **TIM1 thermal material is applied in advanced**

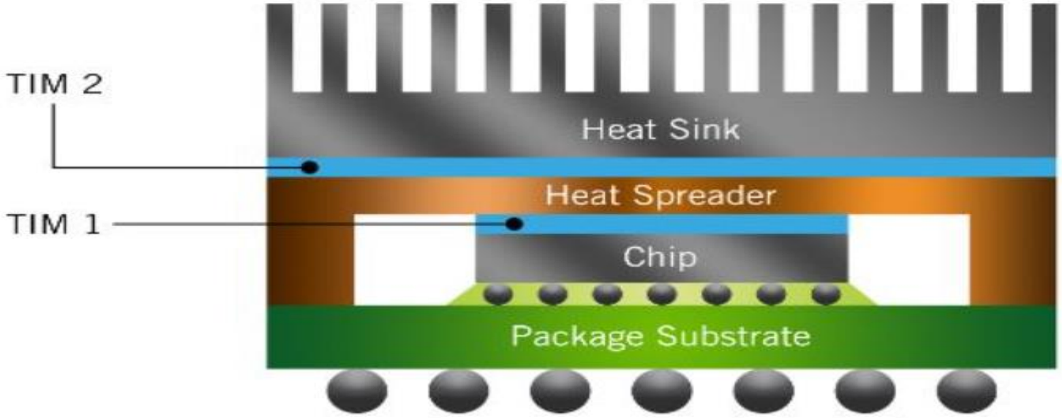
Materials used for TIM1 in the market

	Thermal Conductivity	Issues of the materials
Silicone	8 W/m.K	Low modulus but poor thermal conductivity
graphite	20 W/m.K	Increase adhesive bonding
Indium	80 W/m.K	High thermal conductivity but large modulus

TIM1 material technical specifications
Thermal conductivity : > 80W/m.K
Modulus: < 3GPa
Application size : 65*65mm

→

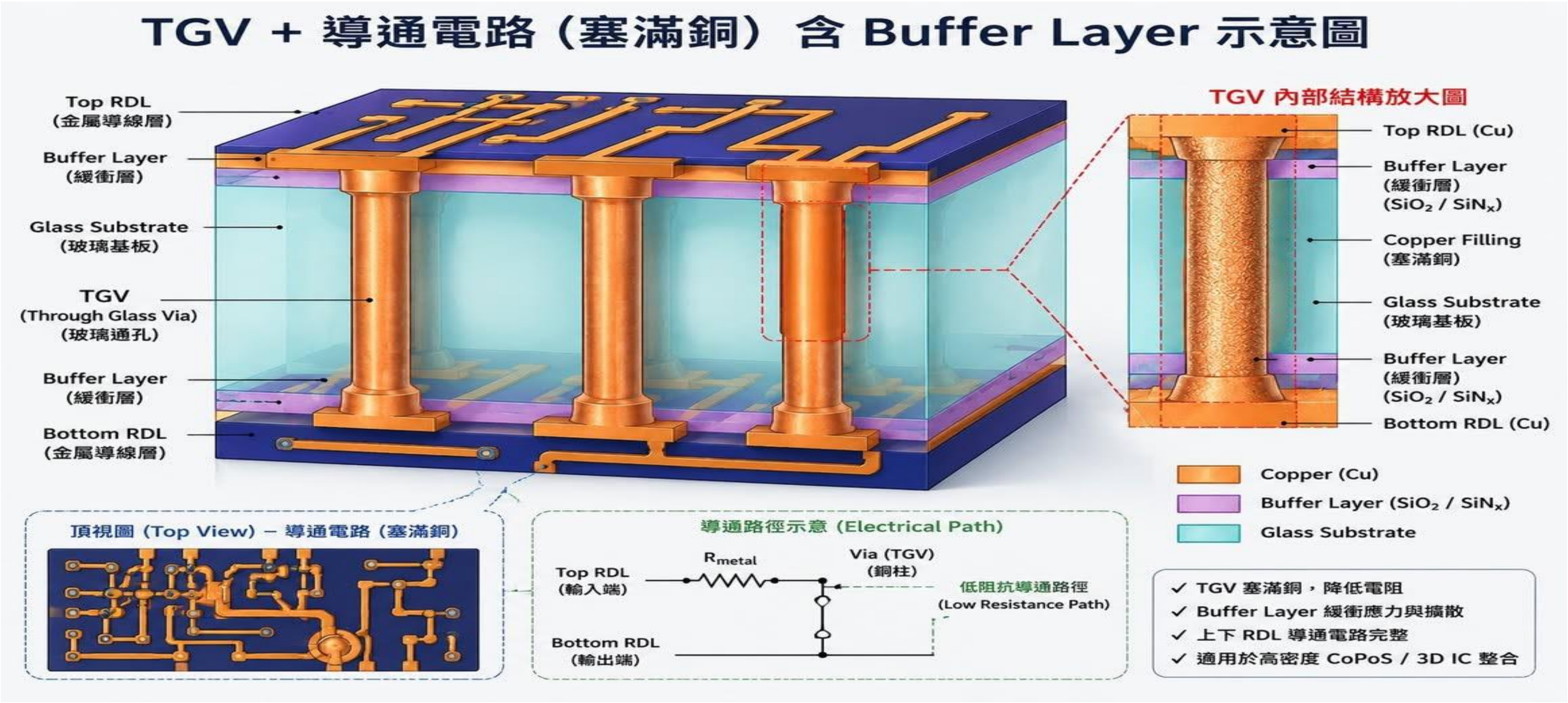
Introducing semi-sintered material for modification
1.High thermal conductivity
2.Low modulus



Application category

(3D Semconductor Advanced Packaging-TGV)

TGV (Through Glass Via) TGV technology enables conductive interconnections in glass substrates



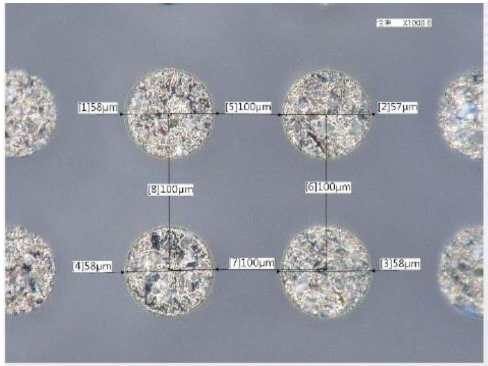
TGV + 導通電路（塞滿銅）含 Buffer Layer 示意圖

- ✓ TGV 塞滿銅，降低電阻
- ✓ Buffer Layer 緩衝應力與擴散
- ✓ 上下 RDL 導通電路完整
- ✓ 適用於高密度 CoPoS / 3D IC 整合

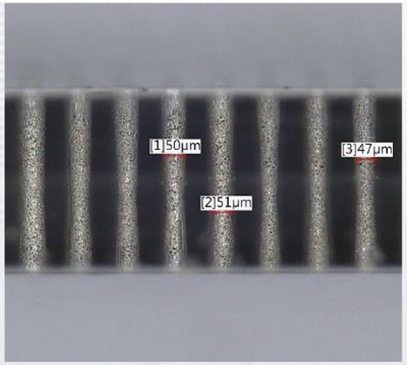
Application category
(3D Advanced Packaging Portfolio)

Diameter：60 um
Aspect ratio：1：8.3

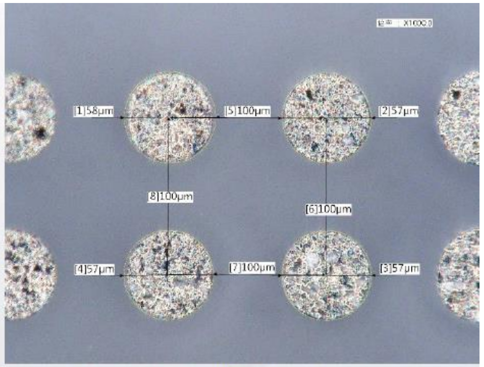
- **Hole filling& glass adhesion:Pass**



Via Φ60um & filled Alloy Cu (Top)



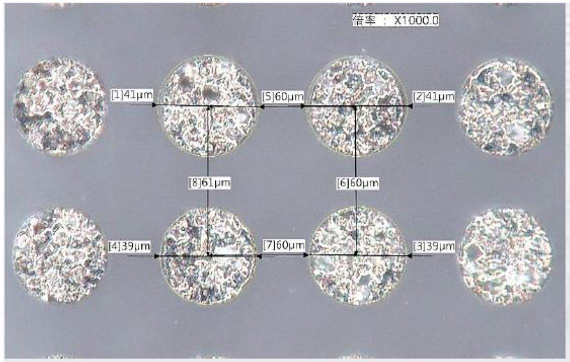
Via Φ60um & filled Alloy Cu (X-section)



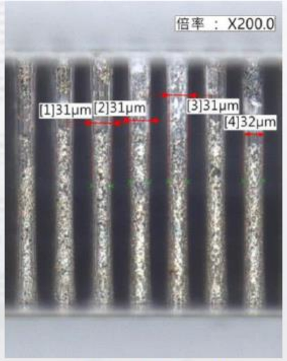
Via Φ60um & filled Alloy Cu (Bottom)

Diameter：40 um
Aspect ratio：1：12.5

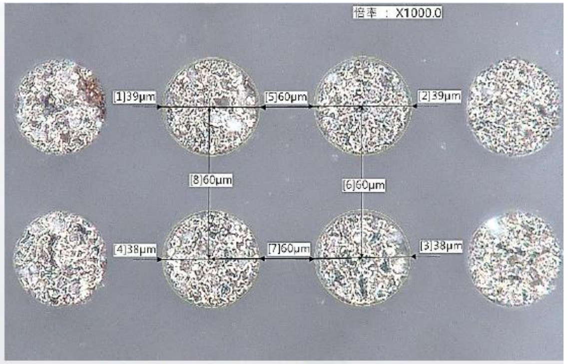
- **Hole filling& glass adhesion:Pass**



Via Φ40um & filled Alloy Cu (Top)



Via Φ40um & filled Alloy Cu (X-section)



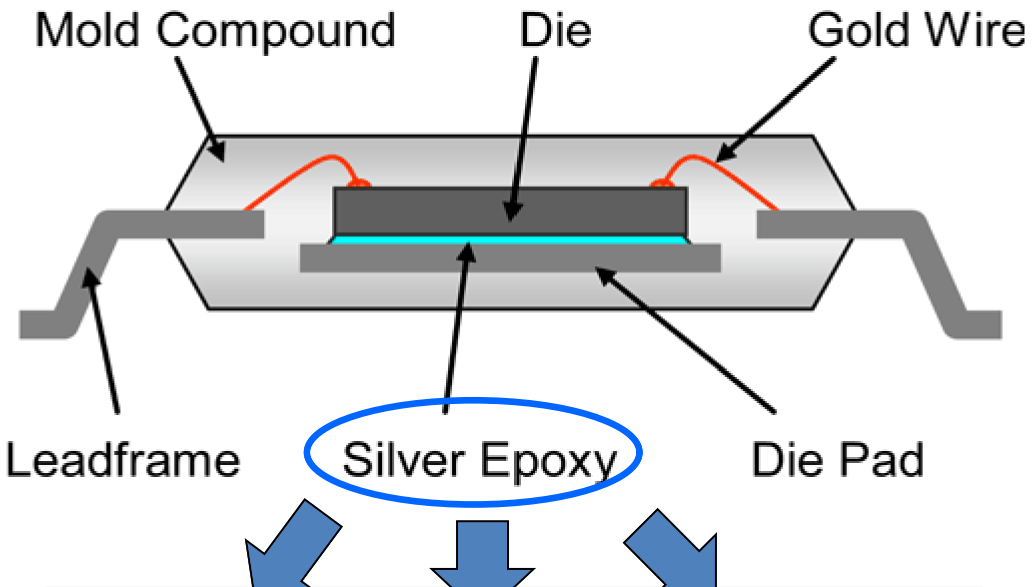
Via Φ40um & filled Alloy Cu (Bottom)

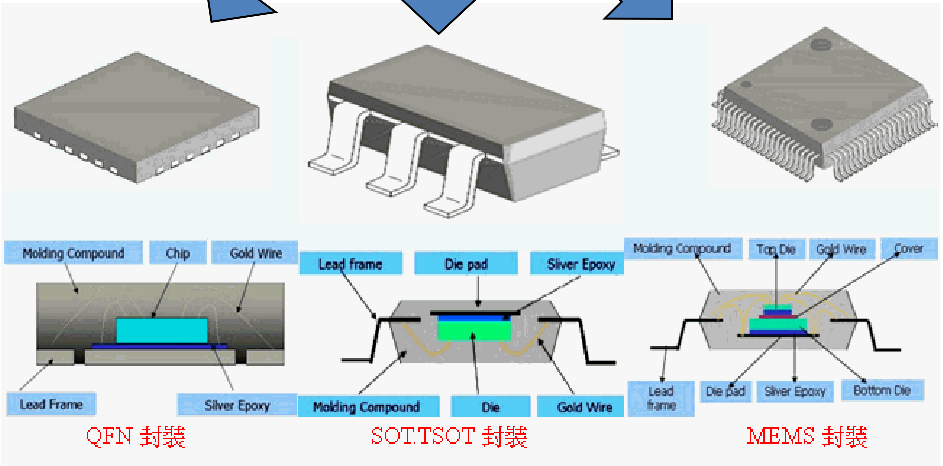
Application for Semi-conductor

Packaging material

Applications @ Semiconductor and LED Packaging

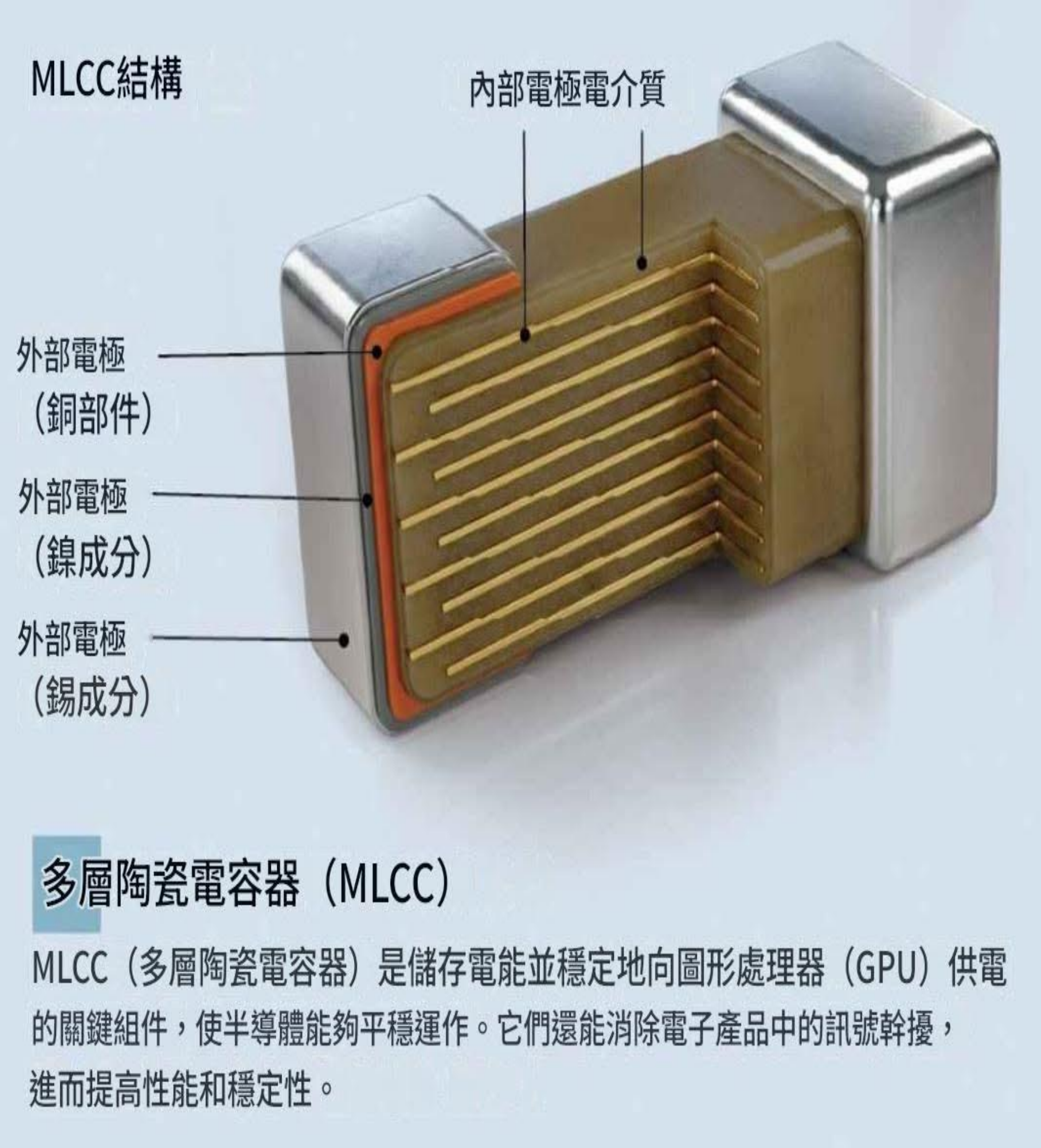
導線架 Die Bonding





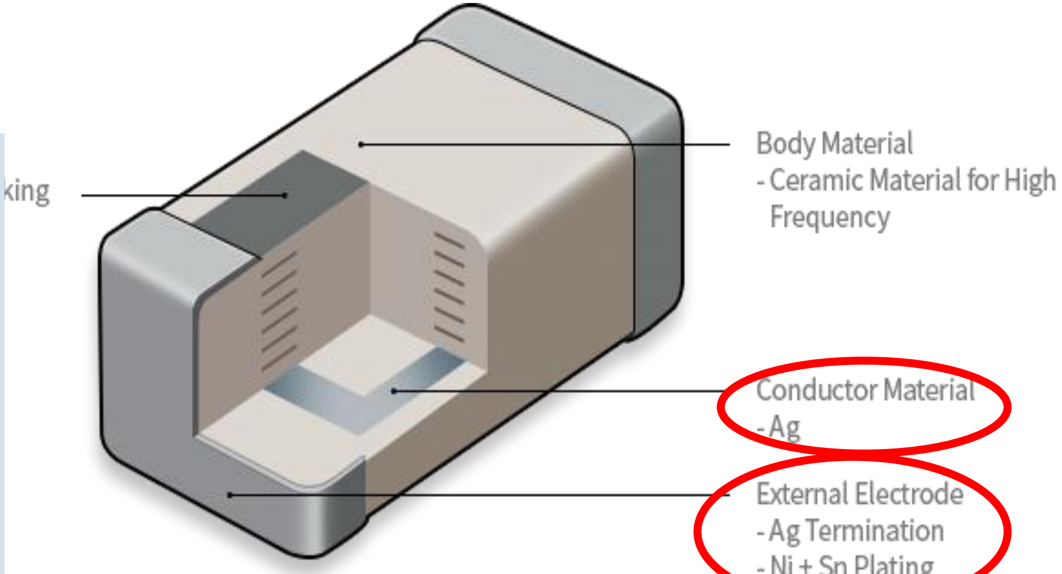
Application for Passive Components

MLCC Capacitor



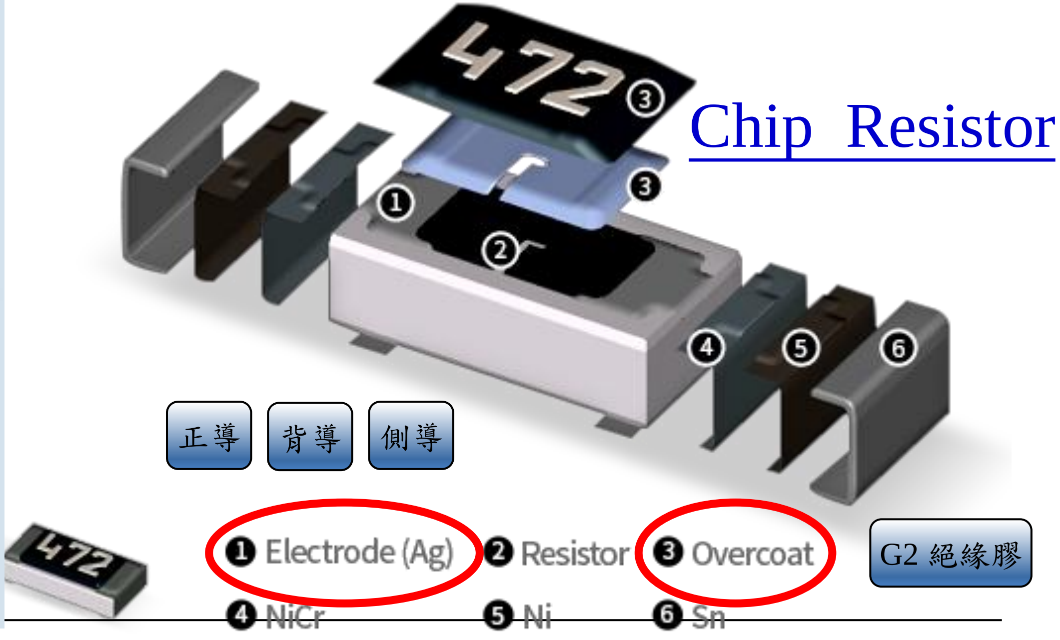
多層陶瓷電容器（MLCC）

MLCC（多層陶瓷電容器）是儲存電能並穩定地向圖形處理器（GPU）供電的關鍵組件，使半導體能夠平穩運作。它們還能消除電子產品中的訊號幹擾，進而提高性能和穩定性。

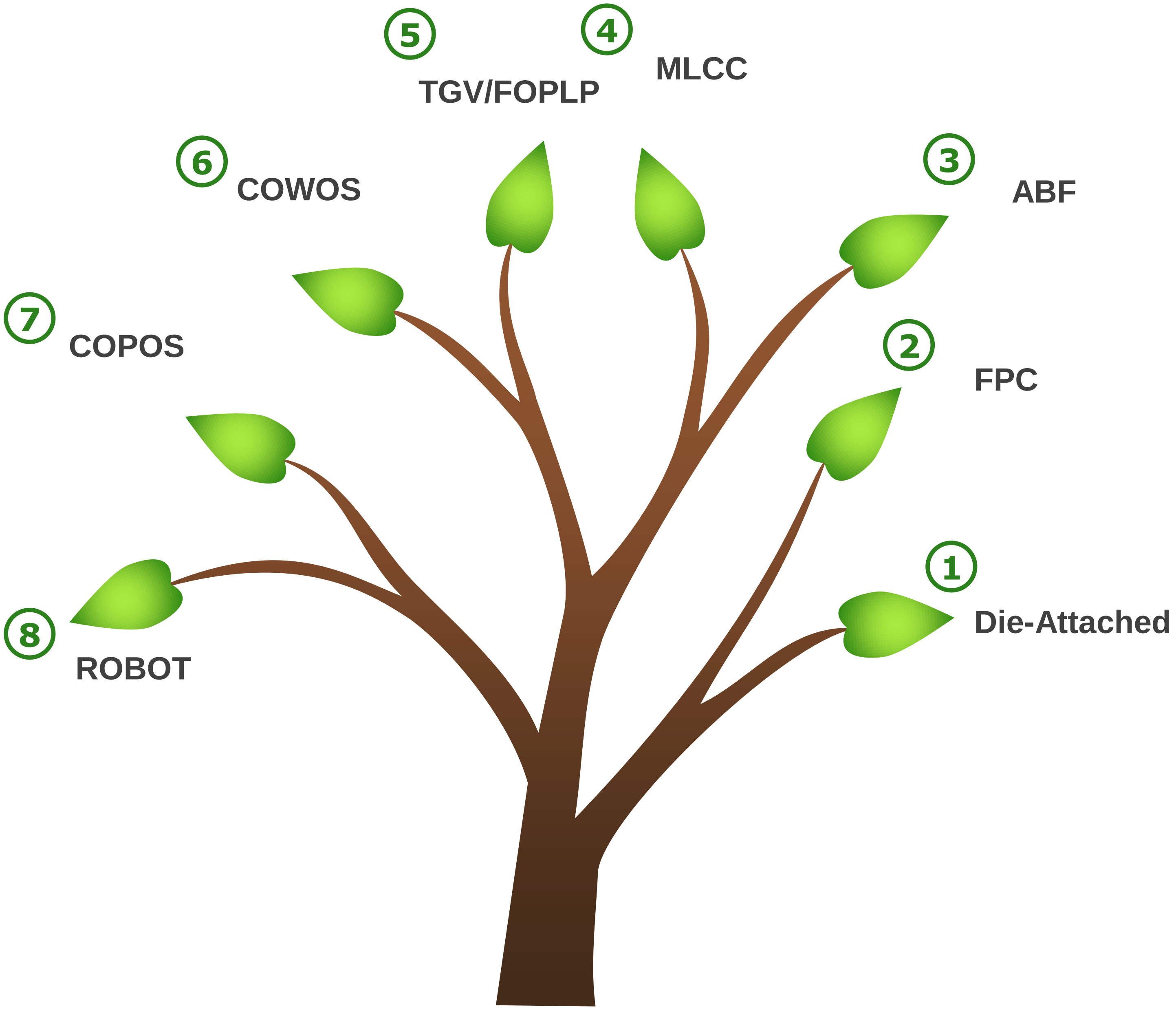


MLCI Chip Inductor

Chip Resistor



Growth Projects



① Die-Attached

② FPC

③ ABF

④ MLCC

⑤ TGV/FOPLP

⑥ COWOS

⑦ COPOS

⑧ ROBOT

Thanks for Listening

Q & A